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October 2014

FGH40N60SMD 600 V, 40 A Field Stop IGBT

Features

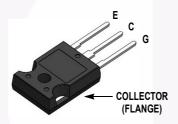
- Maximum Junction Temperature : T_J = 175°C
- Positive Temperaure Co-efficient for Easy Parallel Operating
- · High Current Capability
- Low Saturation Voltage: $V_{CE(sat)}$ = 1.9 V(Typ.) @ I_C = 40 A
- · High Input Impedance
- Fast Switching: E_{OFF} = 6.5 uJ/A
- · Tighten Parameter Distribution
- · RoHS Compliant

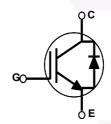
Applications

· Solar Inverter, UPS, Welder, PFC, Telecom, ESS

General Description

Using novel field stop IGBT technology, Fairchild's new series of field stop 2nd generation IGBTs offer the optimum performance for solar inverter, UPS, welder, telecom, ESS and PFC applications where low conduction and switching losses are essential.





Absolute Maximum Ratings

Symbol	Description		Ratings	Unit
V _{CES}	Collector to Emitter Voltage		600	V
V _{GES}	Gate to Emitter Voltage		± 20	V
	Transient Gate to Emitter Voltage		± 30	V
lo.	Collector Current	@ T _C = 25°C	80	A
lc	Collector Current	@ T _C = 100°C	40	Α
I _{CM (1)}	Pulsed Collector Current	@ T _C = 25°C	120	Α
I _F	Diode Forward Current	@ T _C = 25°C	40	Α
	Diode Forward Current	@ T _C = 100°C	20	Α
I _{FM (1)}	Pulsed Diode Maximum Forward Current		120	Α
P _D	Maximum Power Dissipation	@ T _C = 25°C	349	W
י ט	Maximum Power Dissipation	@ T _C = 100°C	174	W
T _J	Operating Junction Temperature		-55 to +175	°C
T _{stg}	Storage Temperature Range		-55 to +175	°C
T _L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 secon	ds	300	°C

Notes

1: Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.43	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	1.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGH40N60SMD	FGH40N60SMD	TO-247	Tube	N/A	N/A	30

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0 \text{ V}, I_{C} = 250 \mu\text{A}$	600	-	-	V
$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 \text{ V, } I_{C} = 250 \mu\text{A}$	-	0.6	-	V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0 V$	- \	, -	250	μА
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	± 400	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 250 \mu A, V_{CE} = V_{GE}$	3.5	4.5	6.0	V
()		I _C = 40 A, V _{GE} = 15 V	-	1.9	2.5	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 40 A, V _{GE} = 15 V, T _C = 175°C	-	2.1	-	V
Dynamic C	haracteristics		•			
C _{ies}	Input Capacitance	V _{CE} = 30 V, V _{GE} = 0 V,	-	1880	-	pF
C _{oes}	Output Capacitance		-	180	-	pF
C _{res}	Reverse Transfer Capacitance	f = 1 MHz	-	50	-	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time		-	12	16	ns
t _r	Rise Time		-	20	28	ns
t _{d(off)}	Turn-Off Delay Time	V _{CC} = 400 V, I _C = 40 A,	-	92	120	ns
t _f	Fall Time	$R_G = 6 \Omega, V_{GE} = 15 V,$	-	13	17	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C	-	0.87	1.30	mJ
E _{off}	Turn-Off Switching Loss		-	0.26	0.34	mJ
E _{ts}	Total Switching Loss		-	1.13	1.64	mJ
t _{d(on)}	Turn-On Delay Time		-	15	-	ns
t _r	Rise Time		-	22	-	ns
t _{d(off)}	Turn-Off Delay Time	V _{CC} = 400 V, I _C = 40 A,	-	116	-	ns
t _f	Fall Time	$R_G = 6 \Omega$, $V_{GE} = 15 V$,	-	16	-	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 175°C	-	0.97	-	mJ
E _{off}	Turn-Off Switching Loss		-	0.60	-	mJ
E _{ts}	Total Switching Loss		-	1.57	-	mJ

Electrical Characteristics of the IGBT (Continued)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Unit
Q_g	Total Gate Charge	V _{CE} = 400 V, I _C = 40 A, V _{GE} = 15 V	-	119	180	nC
Q _{ge}	Gate to Emitter Charge		-	13	20	nC
Q _{gc}	Gate to Collector Charge		-	58	90	nC

Electrical Characteristics of the Diode T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Unit
V _{FM}	Diode Forward Voltage	I _E = 20 A	$T_{\rm C} = 25^{\rm o}{\rm C}$	-	2.3	2.8	V
V FM	Blode Forward Vellage	1F 2071	$T_{\rm C} = 175^{\rm o}{\rm C}$	-	1.67	-	
E _{rec}	Reverse Recovery Energy		T _C = 175°C	-	48.9	-	uJ
t _{rr} Dic	Diode Reverse Recovery Time	I _F =20 A, dI _F /dt = 200 A/μs	$T_C = 25^{\circ}C$	/ -	36	-	ns
			$T_{\rm C} = 175^{\rm o}{\rm C}$	-	110	-	
Q _{rr}	Diode Reverse Recovery Charge		$T_C = 25^{\circ}C$	-	46.8	-	nC
~ I	2.000 riororos riosorory emange		$T_{\rm C} = 175^{\rm o}{\rm C}$	-	445	-	

Figure 1. Typical Output Characteristics

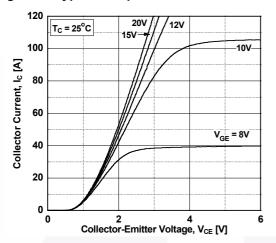


Figure 3. Typical Saturation Voltage Characteristics

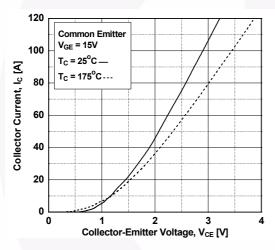


Figure 5. Saturation Voltage vs. V_{GE}

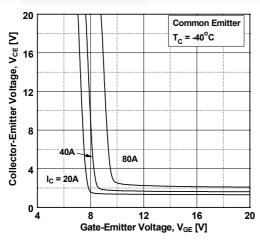


Figure 2. Typical Output Characteristics

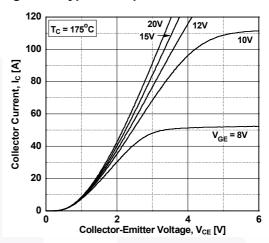


Figure 4. Saturation Voltage vs. Case
Temperature at Variant Current Level

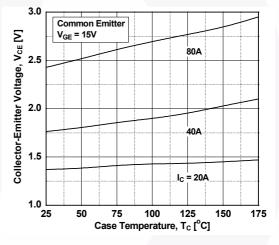


Figure 6. Saturation Voltage vs. V_{GE}

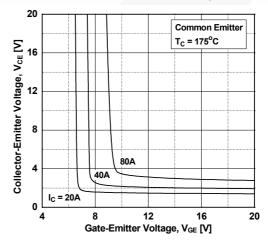


Figure 7. Capacitance Characteristics

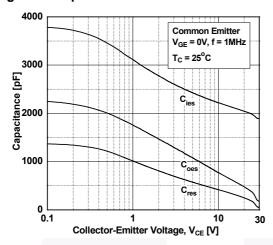


Figure 8. Gate charge Characteristics

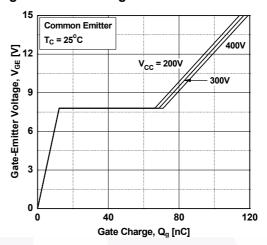


Figure 9. Turn-on Characteristics vs.
Gate Resistance

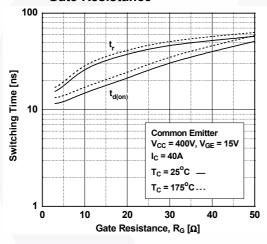


Figure 10. Turn-off Characteristics vs.
Gate Resistance

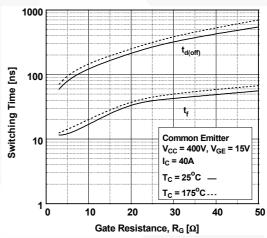


Figure 11. Switching Loss vs.
Gate Resistance

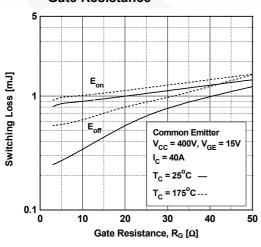


Figure 12. Turn-on Characteristics vs. Collector Current

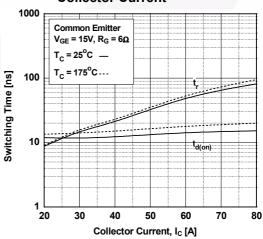


Figure 13. Turn-off Characteristics vs. Collector Current

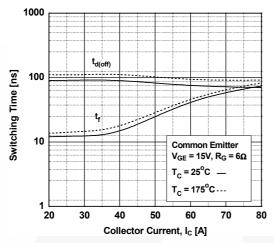


Figure 15. Load Current Vs. Frequency

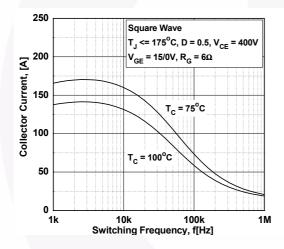


Figure 17. Forward Characteristics

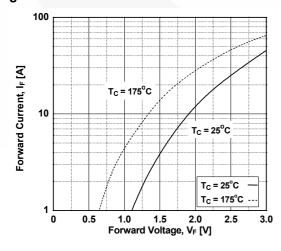


Figure 14. Switching Loss vs. Collector Current

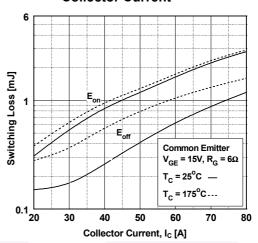


Figure 16. SOA Characteristics

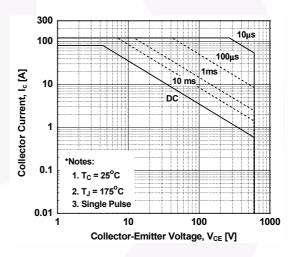


Figure 18. Reverse Recovery Current

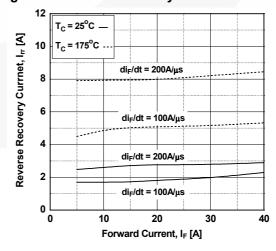


Figure 19. Reverse Recovery Time

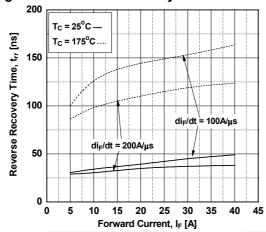


Figure 20. Stored Charge

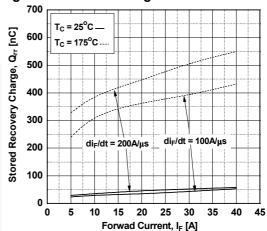


Figure 21. Transient Thermal Impedance of IGBT

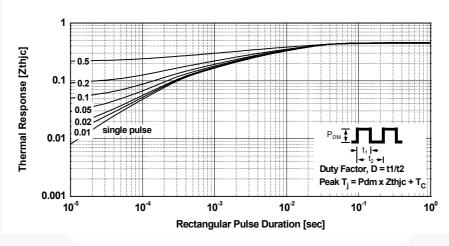
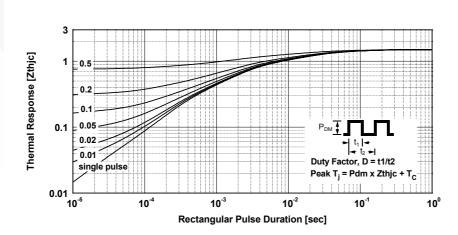
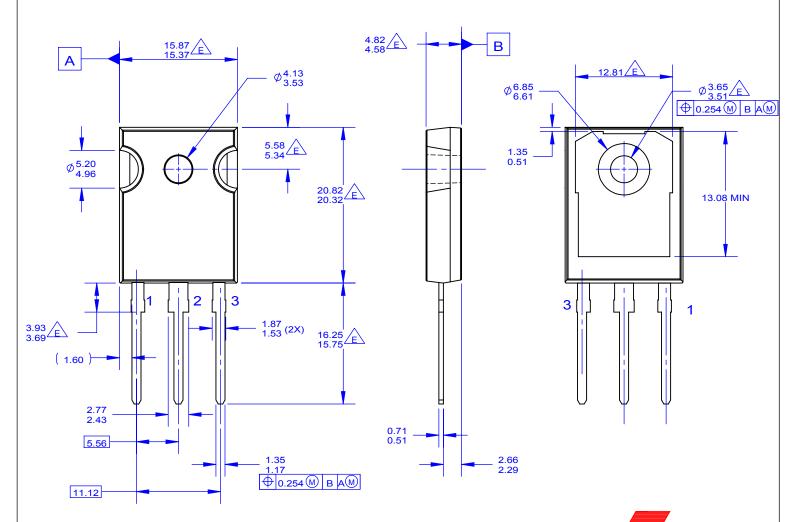


Figure 22. Time Transient Thermal Impedance of Diode







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